



60V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _C = +25°C	
-60V	$150 \text{m}\Omega$ @ V_{GS} = -10 V	-9.4A	
-00 <i>V</i>	185mΩ @ V _{GS} = -4.5V	-8.5A	

Description

This MOSFET has been designed to minimize the on-state resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Backlighting
- DC-DC Converters
- · Power management functions

Features

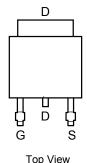
- 100% Unclamped Inductive Switch (UIS) test in production
- Low on-resistance
- Fast switching speed
- Totally Lead-Free & Fully RoHS compliant (Note 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

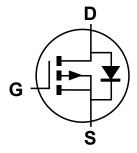
- Case: TO252
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 63
- Weight: 0.33 grams (approximate)



Top View



Pin-Out



Equivalent Circuit

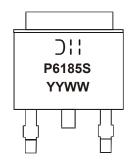
Ordering Information (Notes 4)

Product	Case	Packaging
DMP6185SK3-13	TO252	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html .

Marking Information



Oll = Manufacturer's Marking
P6185S = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 13 = 2013)
WW = Week (01 - 53)



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V_{DSS}	-60	V		
Gate-Source Voltage	V _{GSS}	±20	V		
Continuous Drain Current (Note 6) V _{GS} = -10V	I _D	-3.6 -2.8	А		
Maximum Body Diode Continuous Current	I _S	-2	Α		
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	-15	Α		
Avalanche Current (Notes 7) L = 0.1mH			I _{AS}	-16	Α
Avalanche Energy (Notes 7) L = 0.1mH			E _{AS}	13	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Total Bayor Dissipation (Note 5)	$T_A = +25^{\circ}C$	C	1.6	- W
Total Power Dissipation (Note 5)	T _A = +70°C	P_{D}	1.0	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	D	75	°C/W
Themal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	38	
Total Power Dissipation (Note 6)	T _A = +25°C	ь	2.8	W
Total Power Dissipation (Note 6)	T _A = +70°C	P_{D}	1.8	
Thermal Desigtance, Junction to Ambient (Note 6)	Steady state	0	44	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	20	
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta JC}$	6.2		
Operating and Storage Temperature Range	$T_{J_i} T_{STG}$	-55 to +150	°C	

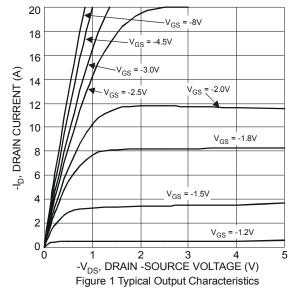
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

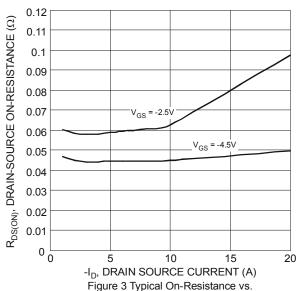
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	-60	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	-	_	-1	μΑ	$V_{DS} = -48V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(th)}	-1.0		-3.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Chatia Dunin Course On Desistance			120	150	_	$V_{GS} = -10V, I_D = -12A$	
Static Drain-Source On-Resistance	R _{DS} (ON)	_	150	185	mΩ	V _{GS} = -4.5V, I _D = -8A	
Diode Forward Voltage	V _{SD}	_	-0.75	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	708	_	pF	.,	
Output Capacitance	Coss	_	39	_	pF	$V_{DS} = -30V, V_{GS} = 0V,$	
Reverse Transfer Capacitance	Crss	-	32	_	pF	f = 1.0MHz	
Gate Resistance	Rg		17	40	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	6.2	_	nC		
Total Gate Charge (V _{GS} = -10V)	Qg	_	14	_	nC	\/ - 20\/ - 40A	
Gate-Source Charge	Qgs	-	2.8	_	nC	$V_{DS} = -30V, I_{D} = -12A$	
Gate-Drain Charge	Qgd	_	3.1	_	nC		
Turn-On Delay Time	tD(on)	-	5.2	_	ns		
Turn-On Rise Time	tr	_	23	_	ns	$V_{DS} = -30V, R_{L} = 2.5\Omega$	
Turn-Off Delay Time	tD(off)	-	33	_	ns	$V_{GS} = -10V, R_{G} = 3\Omega$	
Turn-Off Fall Time	tf		39	_	ns	1	
Body Diode Reverse Recovery Time	trr		22	_	ns	L = 12A di/dt = 100A/us	
Body Diode Reverse Recovery Charge	Qrr		17	_	nC	$I_F = -12A$, di/dt = 100A/ μ s	

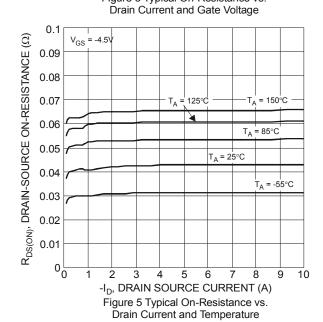
Notes:

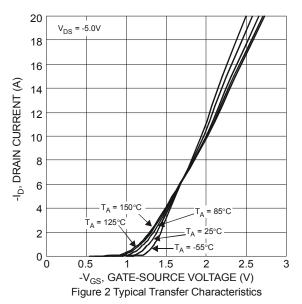
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep TJ = 25°C
- 8. Short duration pulse test used to minimize self-heating effect. 9. Guaranteed by design. Not subject to product testing.

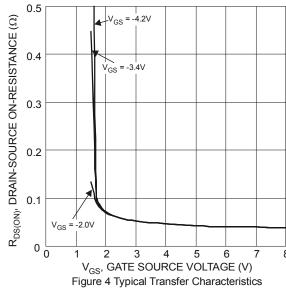


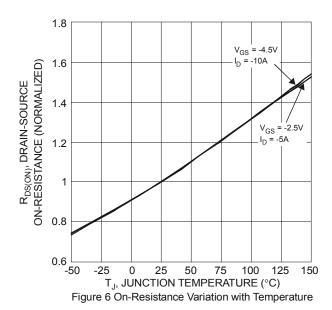




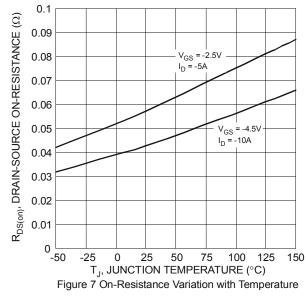


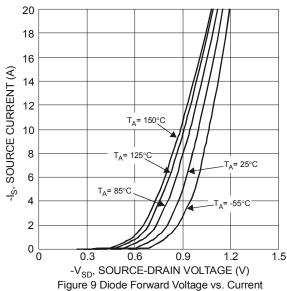


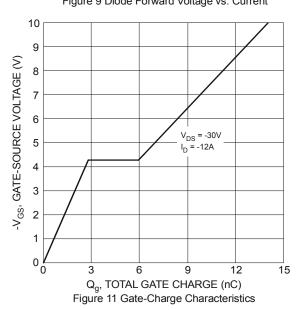












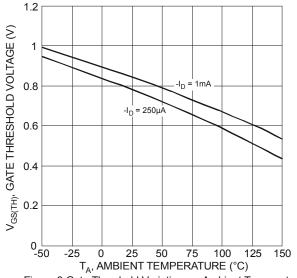
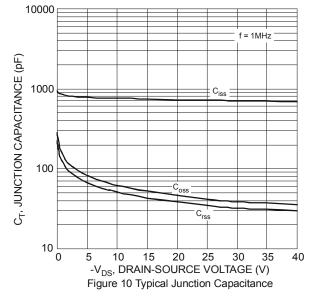


Figure 8 Gate Threshold Variation vs. Ambient Temperature



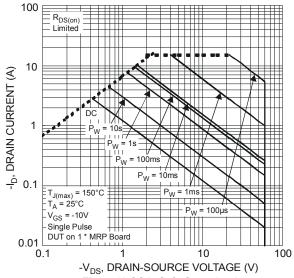
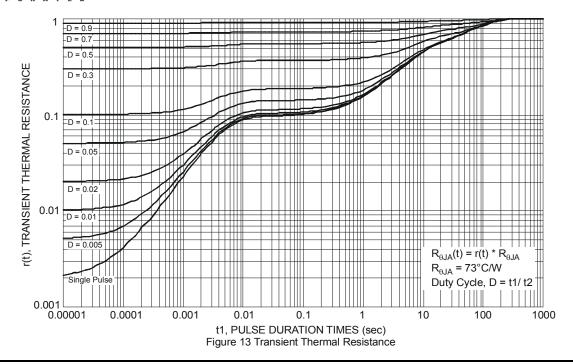


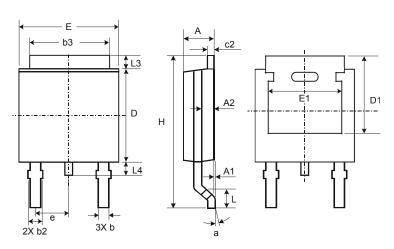
Figure 12 SOA, Safe Operation Area





Package Outline Dimensions

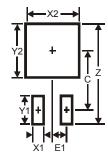
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



TO252						
Dim	Min	Max	Тур			
Α	2.19	2.39	2.29			
A1	0.00	0.13	0.08			
A2	0.97	1.17	1.07			
b	0.64	0.88	0.783			
b2	0.76	1.14	0.95			
b3	5.21	5.46	5.33			
c2	0.45	0.58	0.531			
D	6.00	6.20	6.10			
D1	5.21	_	-			
е	_	_	2.286			
Е	6.45	6.70	6.58			
E1	4.32	_	_			
Н	9.40	10.41	9.91			
L	1.40	1.78	1.59			
L3	0.88	1.27	1.08			
L4	0.64	1.02	0.83			
а	0°	10°	_			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)		
Z	11.6		
X1	1.5		
X2	7.0		
Y1	2.5		
Y2	7.0		
С	6.9		
E1	2.3		



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